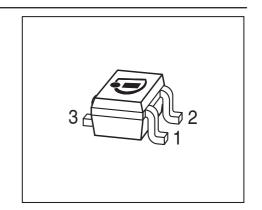


## Low Noise Silicon Bipolar RF Transistor

- For low noise, high-gain amplifiers up to 2 GHz
- For linear broadband amplifiers
- $f_T$  = 8 GHz,  $NF_{min}$  = 1 dB at 900 MHz
- Pb-free (RoHS compliant) package
- Qualification report according to AEC-Q101 available





## ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR193W	RCs	1 = B	2 = E	3 = C	SOT323

**Maximum Ratings** at  $T_A$  = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	12	V
Collector-emitter voltage	$V_{CES}$	20	
Collector-base voltage	$V_{\mathrm{CBO}}$	20	
Emitter-base voltage	$V_{EBO}$	2	
Collector current	I <sub>C</sub>	80	mA
Base current	I <sub>B</sub>	10	
Total power dissipation <sup>1)</sup>	P <sub>tot</sub>	580	mW
<i>T</i> <sub>S</sub> ≤ 63°C			
Junction temperature	TJ	150	°C
Storage temperature	$T_{Stg}$	-55 150	

#### **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	R <sub>thJS</sub>	150	K/W

1

 $<sup>{}^{1}</sup>T_{\rm S}$  is measured on the collector lead at the soldering point to the pcb

 $<sup>^2</sup>$ For calculation of  $R_{\mathrm{thJS}}$  please refer to Application Note AN077 (Thermal Resistance Calculation)



# **Electrical Characteristics** at $T_A$ = 25 °C, unless otherwise specified

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	12	-	-	V
$I_{\rm C}$ = 1 mA, $I_{\rm B}$ = 0					
Collector-emitter cutoff current	I <sub>CES</sub>	-	-	100	μΑ
$V_{CE} = 20 \text{ V}, V_{BE} = 0$					
Collector-base cutoff current	I <sub>CBO</sub>	-	-	100	nA
$V_{\text{CB}} = 10 \text{ V}, I_{\text{E}} = 0$					
Emitter-base cutoff current	I <sub>EBO</sub>	-	-	1	μΑ
$V_{\rm EB}$ = 1 V, $I_{\rm C}$ = 0					
DC current gain	h <sub>FE</sub>	70	100	140	-
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, pulse measured					



**Electrical Characteristics** at  $T_{\Delta}$  = 25 °C, unless otherwise specified

Parameter  Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling	g)	T	T	T	
Transition frequency	f <sub>T</sub>	6	8	-	GHz
$I_{\rm C}$ = 50 mA, $V_{\rm CE}$ = 8 V, $f$ = 500 MHz					
Collector-base capacitance	C <sub>cb</sub>	-	0.74	1	pF
$V_{\text{CB}} = 10 \text{ V}, f = 1 \text{ MHz}, V_{\text{BE}} = 0$ ,					
emitter grounded					
Collector emitter capacitance	C <sub>ce</sub>	-	0.28	-	
$V_{CE} = 10 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$ ,					
base grounded					
Emitter-base capacitance	C <sub>eb</sub>	-	1.8	-	
$V_{\text{EB}} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{\text{CB}} = 0$ ,					
collector grounded					
Minimum noise figure	NF <sub>min</sub>				dB
$I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$ ,					
f = 900 MHz		-	1	-	
f = 1.8 GHz		-	1.6	-	
Power gain, maximum available <sup>1)</sup>	G <sub>ma</sub>				
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm Sopt,}$ $Z_{\rm L}$ = $Z_{\rm Lopt}$ ,					
f = 900 MHz		-	16	-	
f = 1.8 GHz		-	10.5	-	
Transducer gain	$ S_{21e} ^2$				dB
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 $\Omega$ ,					
f = 900 MHz		-	13.5	-	
f = 1.8 GHz		-	8	-	
Third order intercept point at output <sup>2)</sup>	IP <sub>3</sub>	-	30	-	dBm
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 $\Omega$ ,					
f = 900 MHz					
1dB Compression point	P <sub>-1dB</sub>	-	13	-	
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 8 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 $\Omega$ ,					
f = 900 MHz					
		•			•

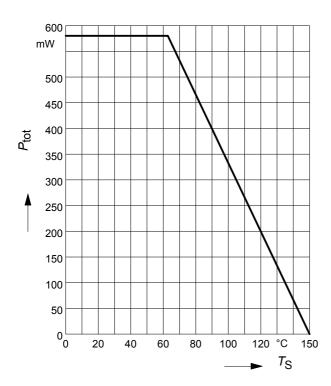
 $<sup>{}^{1}</sup>G_{\text{ma}} = |S_{21} / S_{12}| (k-(k^{2}-1)^{1/2})$ 

<sup>&</sup>lt;sup>2</sup>IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is  $50\Omega$  from 0.2 MHz to 12 GHz



## Total power dissipation $P_{tot} = f(T_S)$

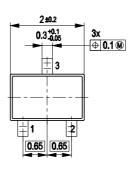


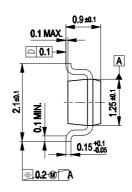
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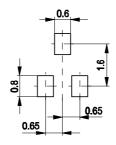
## Package Outline



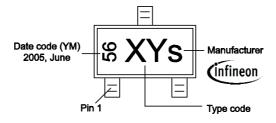




### **Foot Print**

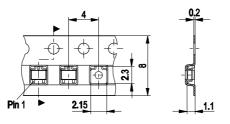


## Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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6

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